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PATENT NUMBER

U.S. **UTILITY** Patent Application

J.S. <b>UTILITY</b> Patent Applic	
O.I.P.E. 16 SCANNED HULLAGS	PATENT DATE

SUBCLASS | AFT UNIT EXAMINER CLASS APPLICATION NO. CONT/PRIOR 738 2811 09/475104 257 NAGESH YODRAHALLI PUS TILAWSIS HIGH PERFORMANCE THERMAL INTERPACE CUPIES PROCESS FOR GREANIC FLIP CHIP PACKAGES TITLE

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